

FCT SiC Standard Materials

<i>FCT-Denotation</i>	SC-S	SC-N	SC-R	SC-Cf
Material	Sintered SiC	Nitride-Bonded SiC ("NSiC", Open Porosity)	Recrystallized SiC ("RSiC", Open Porosity)	C-Longfibre Reinforced SiC ("C/C-SiC")
Process	Pressureless Sintered / Hot Pressed	Gas Pressure Nitridation	Sintered-Recrystallized	Pyrolysis / Liquid Silicon Infiltration
Color	Black	Grey	Black	CFK-Greyish Black
Geometry	Three-Dimensional / Planar Components	Three-Dimensional Components	Three-Dimensional Components	Planar Structures
Maximum size	Ø 700 mm, Length 1900 mm / Ø 400 mm, Thickness 75 mm	Ø 700 mm, Length 1900 mm / Ø 400 mm, Thickness 75 mm	Ø 700 mm, Length 1900 mm / Ø 400 mm, Thickness 75 mm	1000 x 1000 x 15 mm
Application	Mechanical Engineering, Solar and Semiconductor Technology, Chemical Plant Engineering and Construction, Air and Space Applications	Mechanical Engineering, Foundry Technology, Chemical Plant Engineering and Construction, Kiln Technology	Mechanical Engineering, Chemical Plant Engineering and Construction, Kiln Technology	Mechanical Engineering, Tribology and Brake Components
General Properties				
Chemical Composition	SiC	Si ₃ N ₄ / SiC	SiC	SiC / Si / C
Sinter Additives / Fibre Content	C / B ₄ C	Y ₂ O ₃ / Al ₂ O ₃	SiO ₂	C-Fibre (0/90°)
Density ρ [1] (%)	3.08 – 3.17	2.77 – 2.82	2.50 – 2.60	1.90 – 2.30
Residual Porosity (%)	< 3	10 – 12	18 – 20	< 5
Open Porosity Thereof (%)	0	10 – 12	18 – 20	< 0,5
Grain Size (Length) (µm)	1 – 5	1 – 150	1 – 150	-
Mechanical Properties				
Compressive Strength (MPa)	> 2500	600 – 700	-	-
Bending Strength σ _{RT} [2] (MPa)	460	180	80	70 – 200
Weibull-Modulus m	12	20	20	-
Youngs Modulus E (GPa)	420	240	240	15 – 30
Hardness HV [3] (GPa)	26.0	-	-	-
Fracture Toughness K _{Ic} [4] (MPam ^{1/2})	3.5	(3.0 – 3.2)	-	9,5
Poissons Ratio ν	0.15	0.2	0.2	-
Thermal Properties				
Maximum Working Temperatures				
- Inert Atmosphere (°C)	1900	1500	1800	1600
- Oxidising Atmosphere (°C)	1650	1500	1600	600
Specific Heat Capacity (J/kgK)	672	-	-	-
Thermal Conductivity λ (20°C) (W/mK)	140	23	23	11
Coefficient of Thermal Expansion	RT-1000 °C (10 ⁻⁶ K ⁻¹)	4.5	4.8	-
	RT- 250 °C (10 ⁻⁶ K ⁻¹)	3.2	-	2.5
	RT ± 20 °C (10 ⁻⁶ K ⁻¹)	2.5	-	-
Thermal Shock Parameter R ₁ [5] (K)	189	150	56	-
Thermal Shock Parameter R ₂ [6] (W/m)	18889	3450	1278	-
Electrical Properties				
Electrical Resistivity (RT) Ωcm	10 ⁻¹ – 10 ⁸	-	-	-
Dielectric Constant (1 MHz)	-	-	-	-

RT = Room Temperature

[1] Determination of density and porosity according to DIN 623-2

[2] Average value of 4-point bending strength at room temperature according to DIN EN 843-1

[3] Hardness according to DIN EN 843-4

[4] Calculated from crack length derived from Vickers hardness indentation, according to Niihara

[5] Critical temperature difference for an infinite high heat transfer (quenching)

[6] Thermal shock coefficient at finite constant heat transfer (slowly heating)

Date: March 2015

The material characteristics listed above are measured at testing samples. They cannot be transferred to components with different size, shape or surface properties. We reserve the right to alter properties within the scope of technical progress or new developments.

Further special SiC grades are available on demand. We also tailor your specific material solution !